

ABSTRACT

THIN RESIN FILMS AND THEIR USE IN LAYUPS

The disclosure provides an improved resin film product is comprised of a partially cured b-staged resin film that has a thickness in the range of 1 mils to about 10 mils and that is disposed between two protective layers, as well as methods for their manufacture and use in the production of layups used to manufacture printed circuit boards.

[Figure 2C]